

Connector for microSD™ Card (Header Type)

SCHD Series



Low-profile with 1.6mm thickness provides improved flexibility in set design.



Features

- A comfortable click feel at insertion.
- Card-guide structure for smoother card insertion.

Applications

- For mobile phones and personal digital assistants

Typical Specifications

Items		Specifications
Structure	Applicable media	microSD™ Card
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Manual insertion/removal
Performance	Operating temperature range	−20℃ to +70℃
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycle	10,000cycles

Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.
Manual insertion/removal	Standard mount	0	Taping	SCHD1A0101

For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
W-SIM

For
Memory
Stick Micro™

For
Memory
Stick™

Combine Type

For
Compact
Flash™

For PC cards
supporting
CardBus

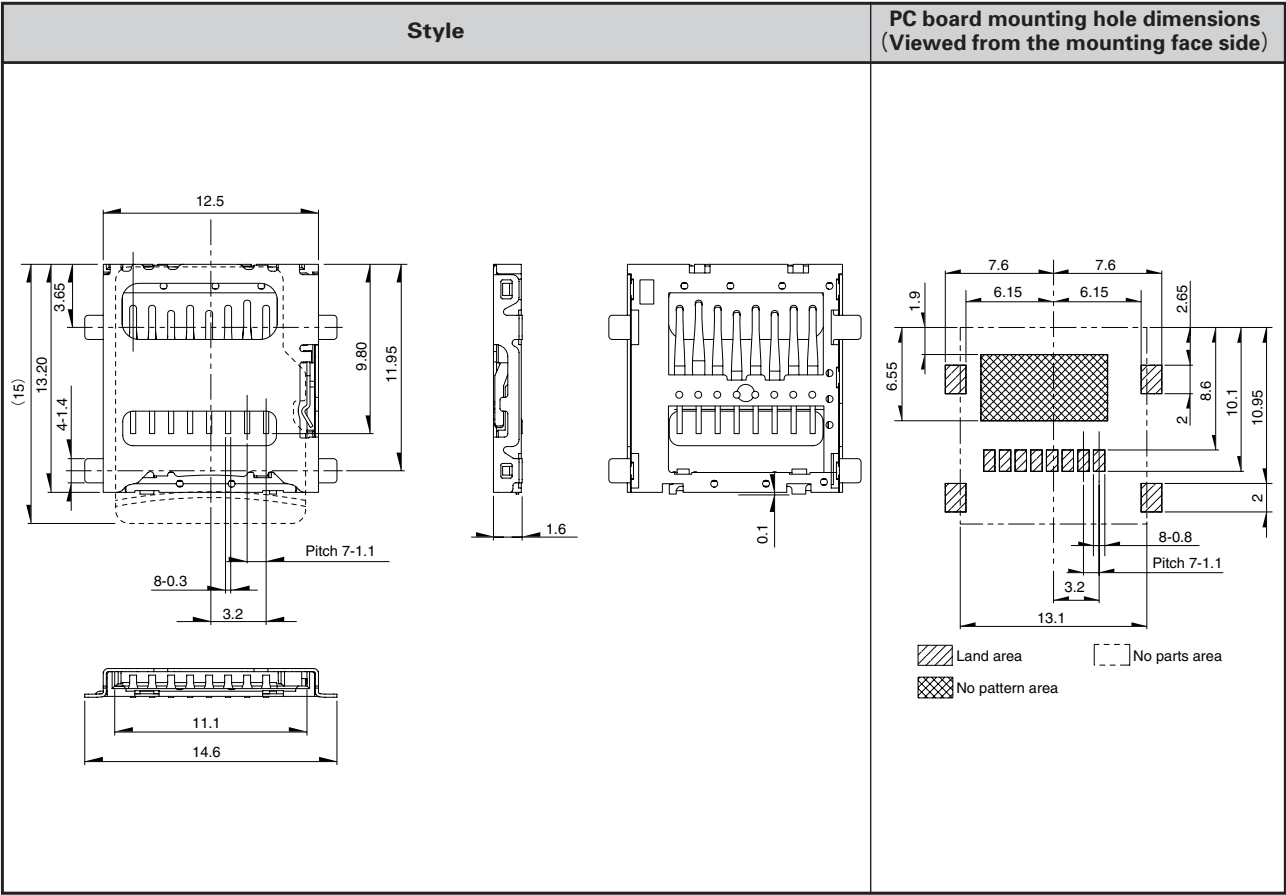
For
Express
Card™

For CMOS
Camera Module

Dimensions

Unit:mm

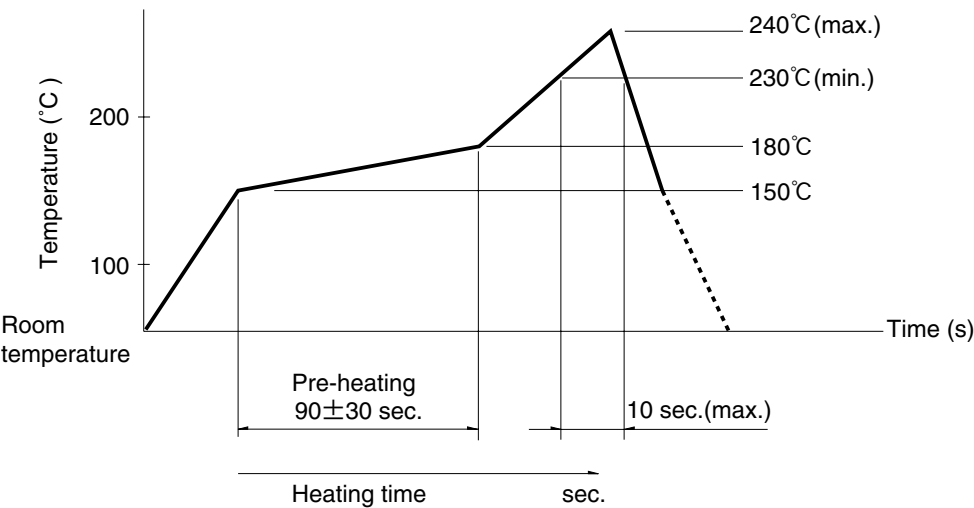
- For SD Memory Card
- For microSD™ Card
- For SIM Card 8pins
- For W-SIM
- For Memory Stick Micro™
- For Memory Stick™
- Combine Type
- For Compact Flash™
- For PC cards supporting CardBus
- For Express Card™
- For CMOS Camera Module



Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) .
- 3. Temperature profile (Surface of products) .



Cautions for using this product

- 1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
- 2. Avoid use of water-soluble soldering flux, since it may corrode the product.
- 3. Check and conform to reflow soldering requirements under actual mass production conditions.
- 4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
- 5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.